NUF2450

2 Line EMI Filter with ESD Protection

This device is a 2 line EMI filter array for audio applications. Greater than −30 dB attenuation is obtained at frequencies from 800 MHz to 5.0 GHz. The NUF2450MU has a cut−off frequency of 20 MHz and minimal line resistance, making it ideal for applications requiring low bandpass attenuation. This UDFN package is specifically designed to enhance EMI filtering for low−profile or slim design electronics especially where space and height is a premium. It also offers ESD protection−clamping transients from static discharges. ESD protection is provided across all capacitors.

Features

- EMI Filtering and ESD Protection
- Integration of 10 Discrete Components
- Compliance with IEC61000−4−2 (Level 4)
  20 kV (Contact)
- UDFN Package, 1.2 x 1.8 mm
- Moisture Sensitivity Level 1
- ESD Ratings: Machine Model = C
  Human Body Model = 3B
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

Benefits

- Reduces EMI/RFI Emissions on Audio Lines
- Low Profile Package; Typical Height of 0.5 mm
- Design−Friendly and Easy−to−Use Pin Configurations, Particularly for Portable Electronics
- Integrated Solution Offers Cost and Space Savings in UDFN Package
- Reduces Parasitic Inductances Which Offer a More “Ideal” Low Pass Filter Response
- Integrated Solution Improves System Reliability
- Excellent ESD Performance with Large GND Pad

Applications

- Headsets, MP3 Players, and PDAs
- Portable DVDs
- Hands−Free Interface

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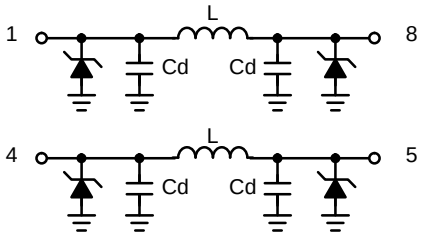
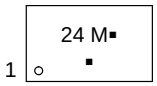


(Top View)

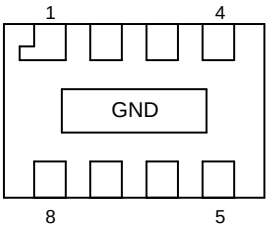
UDFN8
CASE 517AD

MARKING DIAGRAM



24 = Specific Device Code
M = Month Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

PIN CONNECTIONS



(Bottom View)

ORDERING INFORMATION

Device	Package	Shipping†
NUF2450MUT2G	UDFN8 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
ESD Discharge IEC61000−4−2 Contact Discharge Machine Model Human Body Model	V_{PP}	 20 1.6 16	kV
Operating Temperature Range	T_{OP}	−40 to 85	°C
Storage Temperature Range	T_{STG}	−55 to 150	°C
Maximum Lead Temperature for Soldering Purposes (1.8 in from case for 10 s)	T_L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Maximum Reverse Working Voltage	V_{RWM}		−	−	5.0	V
Breakdown Voltage	V_{BR}	I_R = 1.0 mA	6.0	7.0	8.0	V
Leakage Current	I_R	V_{RWM} = 3.3 V	−	−	100	nA
Inductance	L		−	2.3	−	nH
Series Resistance	R_S		0.9	1.3	1.7	Ω
Capacitance (Note 1)	C_{line}	V_R = 0 V, f = 1.0 MHz	190	240	290	pF
Cut−Off Frequency (Note 2)	f_{3dB}	Above this frequency, Appreciable Attenuation Occurs	−	20	−	MHz

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Measured at 25°C.
2. 50 Ω source and 50 Ω load termination.

TYPICAL CHARACTERISTICS

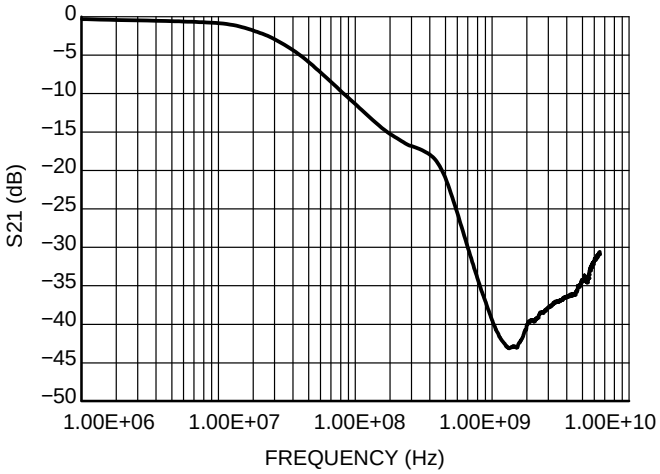


Figure 1. Typical Insertion Loss Characteristics (S21 Measurement)

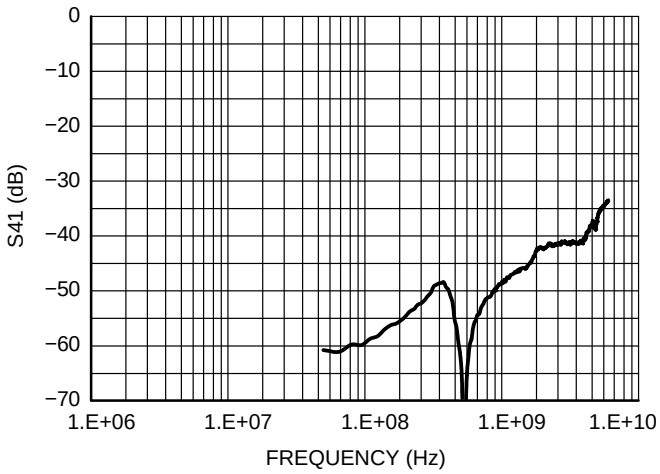


Figure 2. Analog Crosstalk Curve (S41 Measurement)

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

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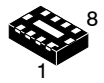
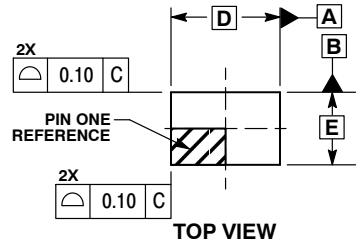
UDFN8 1.8x1.2, 0.4P
CASE 517AD
ISSUE D

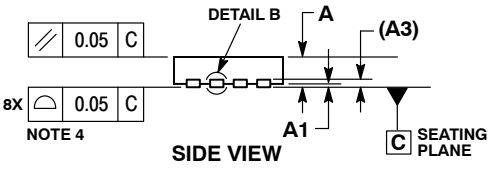
DATE 23 OCT 2012



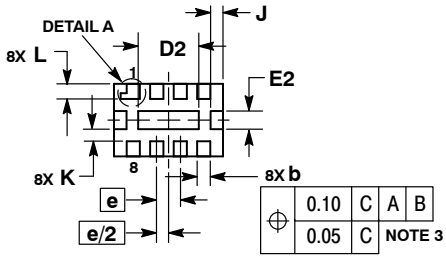
SCALE 4:1



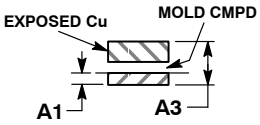
TOP VIEW



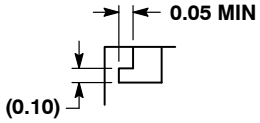
SIDE VIEW



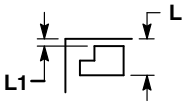
BOTTOM VIEW



DETAIL B
ALTERNATE CONSTRUCTIONS



DETAIL A

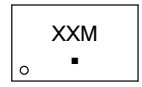


DETAIL A
OPTIONAL CONSTRUCTION

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.80 BSC	
E	1.20 BSC	
e	0.40 BSC	
D2	0.90	1.10
E2	0.20	0.30
J	0.19 REF	
K	0.20 TYP	
L	0.20	0.30
L1	---	0.10

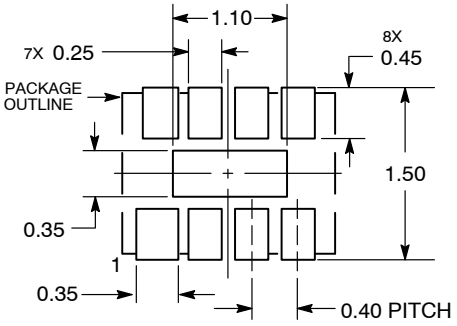
GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code
▪ = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G”, may or not be present.

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	**UDFN8 1.8X1.2, 0.4P**	**PAGE 1 OF 1**

PUBLICATION ORDERING INFORMATION

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